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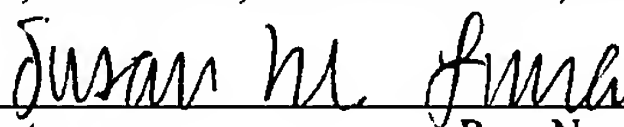
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant : Jingyi Bai et al.
Serial No. : 10/618,220
Filed : July 11, 2003
Title : METHODS FOR FILLING HIGH ASPECT RATIO TRENCHES IN
SEMICONDUCTOR LAYERS
Docket No. : MIO 0109 PA
Art Unit : 2825
Examiner : Renzo Rocchegiani

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 23, 2004.	
	
Agent	Reg. No. 38,769

AMENDMENT

This paper is being filed in response to the Office Action mailed March 26, 2004.
Reconsideration and reexamination are respectfully requested in light of the amendments and remarks below.